



Telecommunications Industry Association

1310 North Courthouse Road, Suite 890
Arlington, VA 22201 | www.tiaonline.org

Approved by General Counsel

TR-42.3 Subcommittee on Pathways, Spaces, Bonding and
Grounding

Meeting Date: 25 January 2022

Location: Teleconference

Approved: 15 February 2022



Meeting Report

TR-42.3 Subcommittee

Telecommunications Administration, Pathways, Spaces, Bonding and Grounding

Date: January 25, 2022
 Time: 3:45 PM -6:00 AM CDT
 Location: Virtual GoToWebinar
 Chair: Cindy Montstream - Legrand
 Vice Chair: Jonathan Jew - J&M Consultants

1. Administrative/General Business

1.1. Call to Order

The chair, Cindy Montstream called the meeting to order at 3:45 PM CST

Attendees were advised of the Important Notice of Participation

IMPORTANT NOTICE OF PARTICIPATION

Participation in, or attendance at, any activity of a TIA Formulating Group or any subelement thereof, constitutes acceptance of and agreement to be bound by all provisions of the current TIA Procedures for American National Standards (PANS) and the TIA Engineering Committee Operating Procedures (ECOP) and permission that all communications and statements, oral or written, or other information disclosed or presented, and any translation or derivative thereof, may without compensation, and to the extent such participant or attendee may legally and freely grant such copyright rights, be distributed, published, and posted on TIA's web site, in whole or in part, on a non-exclusive basis by TIA or TIA's licensees or assignees, or as TIA directs. Exceptions to the foregoing may be granted or permitted in writing to the Chair of the Formulating Group by the head of the TIA Standards Department on a case-by-case basis.

TIA is actively seeking participation in TR-42 standards projects from the user and general interest communities.

1.2. Attendance (Call Quorum, Introductions, Roster)

The attendees introduced themselves and registered attendance using the on-line system. Quorum was verified by roster call. Attendees:

Last Name	First Name	Organization	Last Name	First Name	Organization
Ahmed	Adnan	R&M	Kozischek	David	Corning
Born	Steve	Superior Essex	Larsen	Wayne	CommScope
Ehredt	Al	Telegartner	Lenz	Sean	Panduit
Eisele	Steve	DCS	Maguire	Valerie	The Siemon Co
Emplit	Ray	Harger	Montstream	Cindy	Legrand
Forbes	Diane	NIS	Pace	Joe	Delta Comp Cons
Gallo	Ernest	Ericsson	Poulsen	Jeff	Leviton

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Harpel	Todd	Berk-Tek	Sharp	Peter	Business Net Tech
Hess	Dave	Cord Data	Shuman	Brian	Belden
Jew	Jonathan	J&M Consultants	Tellas	Ronald	Belden
Jones	Richard	Datacom Stds	Valentukonis	Dave	The Siemon Co
Jones	Cameron	ODVA/Rockwell	Winston	William	Fluke
Judson	Ward	nVent Electric	Woodman	Brad	Molex
Keller	David	KellerREC			

1.3. Current Meeting Agenda Review and Approval

The meeting agenda (TR423-2022-01-001) was approved without objection

1.4. Previous Meeting Report Review and Approval

The previous meeting report (TR423-2021-10-020) was approved without objection

1.5. TIA Intellectual Property Rights (Early Disclosure Policy)

The Chair brought to the attention of the attendees the TIA policy regarding intellectual property rights:

TIA's Intellectual Property Rights Policy can be found in Statements of Policy (ANNEX C) and other clauses and annexes of TIA Standards Development Procedures. Participants in the work of the TIA Formulating Groups are urged to review the appropriate sections. Individual participants are encouraged to notify TIA of any patent(s) or published pending patent application(s) of which they are aware that may be essential to the practice of a proposed TIA Publication, including requirements introduced through normative references, early on in the development to reduce the possibility for delays in the development process and increase the likelihood that the proposed TIA Publication will become a Standard. However, a Patent Holder who has provided TIA with a TIA Patent Holder Statement with respect to the applicable proposed TIA Publication need not (but may elect to) identify its specific patent(s) or published pending patent application(s) that may be essential to the practice of the proposed TIA Publication in question. Patent searches are not required to comply with the TIA Intellectual Property Rights Policy.

1.6. Distribution of documents and contributions

The following documents were distributed on TIA Connect in the TR-42.3 Commercial Building Telecommunications Pathways and Spaces community, under Documents, in the TR-42.3 Commercial Building Telecommunications Pathways and Spaces/2022 Meetings/2022-01-Virtual folder



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Document #	Title	Company	Contributor
2021-10-020	Report October 2021 Virtual Meeting	TR-42.3	Jew
2022-01-001	Notice & Agenda January 2022 Virtual Meeting	TR-42.3	Montstream
2022-01-002	Response from NFPA re NEC Article 250.121(b) Impact on TIA-607	Ericsson	Gallo
2022-01-003	TIA-569-E-1 Draft 1	TR-42.3	Emplit
2022-01-004a	TIA-569-E-1 Project Request	TR-42.3	Jew

1.7. List of Standards and TSBs from Subcommittee

Document	Title	Date of Revision	Current Status
ANSI/TIA-569-E	Telecommunications Pathways & Spaces	2019	Published
ANSI/TIA-606-D	Administration Standard For Telecommunications Infrastructure	2021	Published
ANSI/TIA-607-D	Generic Telecommunications Bonding & Grounding (Earthing) For Customer Premises	2019	Published
ANSI/TIA-607-D Addendum 1	Generic Telecommunications Bonding & Grounding (Earthing) For Customer Premises- Addendum 1	2021	Published
ANSI/TIA-5048	Automated Infrastructure Management (Aim) Systems- Requirements, Data Exchange and Applications	2017	Published
ANSI/TIA-5048-1	Automated Infrastructure Management (Aim) Systems- Requirements, Data Exchange and Applications – Addendum 1	2021	Published

1.8. Chair's Report and General Items

1.8.1. TR-42 Opening Plenary Report

TR-42 and all subcommittees including TR-42.3 has been converted from the old website, email reflector, and FTP site to TIA Connect <https://connect.tiaonline.org/home>.

The new TR-42.3 email reflector is TIA-TR423@ConnectedCommunity.org email notifications to your business/personal email accounts do not include the attachments. Email attachments can be retrieved from TIA Connect.

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2. Old Business

2.1. ANSI/TIA-606-D – Revision of TIA-606 Administration

ANSI/TIA-606-D was published in October 2021.

2.2. New NEC Article 250.121(b) Impact on validity of TIA-607

TR-42.3 reviewed TR423-2022-01-002, the NFPA response Re NEC Article 250.121(b) Impact on TIA-607. There is no impact on the validity of TIA-607.

2.3. Other

There was no other old business.

3. New Business

3.1. TIA-569-E-1

TR-42.3 reviewed TIA-569-E-1 Draft 1 (TR423-2022-01-003), which incorporates modifications to TIA-569-E to harmonize with the ASHRAE Thermal Guidelines for Data Processing Environments, 5th edition.

There was a suggestion to add TBDs instead of the ASHRAE numbers. A vote was taken to decide whether to use TBDs or not.

Motion: “Use current draft posted for ballot and do not add TBDs.”

In favor: 10 Oppose: 4 Abstain: 2

The document will be submitted for ballot as posted without TBDs.

TR-42.3 reviewed and unanimously approved the TIA-569-E-1 Project Request (TR423-2022-01-004a). The corrected version was posted as TR423-2022-01-004b.

TR-42.3 unanimously approved an industry ballot for TIA-569-E-1.

3.2. Impact of modification of NEC on TIA-607

TR-42.3 discussed an update to NEC allowing copper-clad steel grounding conductors being permitted for communications applications (800.100A2 and 810.21A) under “other corrosion-resistant conductive material”

TR-42.3 agreed to defer action on this until we fully understand the changes and are certain of the text that will be included in the final version of the 2023 NEC. This will be discussed further at the next TR-42.3 meeting.

3.3. Other new business

There was no other new business.

4. Action Items

- Jonathan Jew to submit the PAR for TIA-569-E-1



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- Ray Emplit to submit industry ballot authorization for TIA-569-E-1
- Jeff Poulsen and Ron Tellas to provide an update regarding allowing copper-clad steel grounding conductors in the NEC at the next TR-42.3 meeting
- Cindy Montstream to create a PAR for reaffirmation of ANSI/TIA-5048 and add it to the agenda of the next TR-42.3 meeting.

5. Upcoming Meetings

5.1. Next meeting

- June 6-10, 2022- Virtual

6. Adjournment

The meeting was adjourned at 5:13 pm CST

This meeting was conducted in accordance with the TIA Legal Guidelines and the engineering procedures.

AVAILABILITY OF MEETING DOCUMENTS:

TR-42 members/participants are instructed to download contributions and other meeting documents from TIA Connect (connect.tiaonline.org) before the meeting.

To access the meeting's contributions, please follow the directions below:

- o Go to connect.tiaonline.org
- o Enter your *Username* (your email address in the TIA database)
- o Enter your *Password*
- o Click "LOGIN"
- o Click the "Communities" tab and then select "All My Communities"
- o Scroll down the page and select "TR-42.3 Commercial Building Telecommunications Pathways and Spaces"
- o Click on "Documents" and then select the subfolder for the meeting

NEW CONTRIBUTIONS:

Contributions shall use the approved templates and specific wording provided by TIA. Contributions affecting a document are to include a TIA cover sheet, proposed text to be included in the document, and the rationale/substantiation for the contribution. File templates are available on TIA Connect under the Standards Procedures Toolbox tab in the Form folder for download. All contributions shall be submitted to the electronic document coordinator (EDC). All electronic files shall be provided in either Adobe Acrobat (*.PDF); Microsoft Word (*.DOC); Microsoft PowerPoint (*.PPT); or in Microsoft Excel (*.XLS). Compressed files shall be accessible using PKUNZIP or WINZIP (*.ZIP).

Early submittal and posting of contributions for consideration in meetings is highly encouraged. Contributions shall be submitted to the EDC as soon as possible and then posted to the appropriate TIA Connect folders by the EDC as soon after receipt as possible, preferably within one business day. All contributions shall be posted to the appropriate location on TIA Connect no later than 12:00 noon EST on

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the Monday preceding the week of the meeting in which the contribution is to be considered (example: if the meeting will be held on Thursday the 20th, the contributions shall be posted by noon on Monday the 10th).

LATE CONTRIBUTIONS:

Contributions not provided to the EDC within 24-hours of the meeting shall be classified as "late contributions." They may be considered in the meeting to which they are addressed at the discretion of the chair. All late contributions shall be provided to the EDC and to the committee members on a memory stick or other electronic media. All late contributions shall be posted to TIA Connect within one week of meeting adjournment.

Questions and comments on this agenda should be submitted to:

Cindy Montstream, Chair	cindy.montstream@legrand.us	(860) 208-5261
Jonathan Jew, Vice-Chair	jew@j-and-m.com	(415) 515-4304